SCLS148F - DECEMBER 1982 - REVISED AUGUST 2003

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Noninverting Outputs Drive Bus Lines Directly or Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I<sub>CC</sub>
- Typical t<sub>pd</sub> = 22 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Bus-Structured Pinout

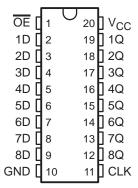
### description/ordering information

These octal edge-triggered D-type flip-flops feature 3-state outputs designed specifically for bus driving. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

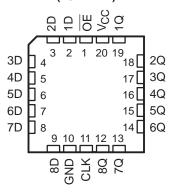
The eight flip-flops enter data on the low-to-high transition of the clock (CLK) input.

A buffered output-enable  $(\overline{OE})$  input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

#### SN54HC574 . . . J OR W PACKAGE SN74HC574 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



## SN54HC574 . . . FK PACKAGE (TOP VIEW)



#### ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74HC574N	SN74HC574N
	SOIC - DW	Tube of 25	SN74HC574DW	HC574
	30IC - DW	Reel of 2000	SN74HC574DWR	ПС574
−40°C to 85°C	SSOP – DB	Reel of 2000	SN74HC574DBR	HC574
	SOP - NS	Reel of 2000	SN74HC574NSR	HC574
		Tube of 70	SN74HC574PW	
	TSSOP - PW	Reel of 2000	SN74HC574PWR	HC574
		Reel of 250	SN74HC574PWT	
	CDIP – J	Tube of 20	SNJ54HC574J	SNJ54HC574J
–55°C to 125°C	CFP – W	Tube of 85	SNJ54HC574W	SNJ54HC574W
	LCCC – FK	Tube of 55	SNJ54HC574FK	SNJ54HC574FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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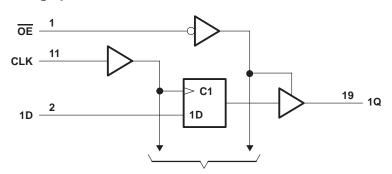
## description/ordering information (continued)

OE does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

#### **FUNCTION TABLE** (each flip-flop)

	INPUTS	OUTPUT	
OE	CLK	D	Q
L	<b>↑</b>	Н	Н
L	$\uparrow$	L	L
L	H or L	Χ	Q <sub>0</sub>
Н	Χ	Χ	Z

## logic diagram (positive logic)



To Seven Other Channels

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>		0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (se	ee Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c) (see Note 1)	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	·	$\dots \dots \pm 35 \text{ mA}$
Continuous current through V <sub>CC</sub> or GND		±70 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	DB package	70°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T <sub>stg</sub>		65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



## recommended operating conditions (see Note 3)

				154HC57	'4	SN	174HC57	'4	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
VCC	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
٧ıH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V
		V <sub>CC</sub> = 6 V	4.2			4.2			
		V <sub>CC</sub> = 2 V			0.5			0.5	
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35			1.35	V
		V <sub>CC</sub> = 6 V			1.8			1.8	
٧ <sub>I</sub>	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns
		V <sub>CC</sub> = 6 V			400			400	
T <sub>A</sub>	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vaa	Т	A = 25°C	;	SN54HC574		SN74HC574		UNIT
PARAMETER	1251 CC	CNDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
		I <sub>OH</sub> = -20 μA	2 V	1.9	1.998		1.9		1.9		
			4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
	VI = VIH or VIL	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1		0.1	
			4.5 V		0.001	0.1		0.1		0.1	
VOL			6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

## SN54HC574, SN74HC574 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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## timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		Vaa		25°C	SN54H	C574	SN74HC574		UNIT
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V		6		4		5	
fclock	Clock frequency	4.5 V		30		20		24	MHz
		6 V		38		24		28	
		2 V	80		120		100		
t <sub>W</sub>	Pulse duration, CLK high or low	4.5 V	16		24		20		ns
		6 V	14		20		17		
		2 V	100		150		125		
t <sub>su</sub>	Setup time, data before CLK↑	4.5 V	20		30		25		ns
		6 V	17		26		21		
		2 V	5		5		5		ns
th	Hold time, data after CLK↑	4.5 V	5		5		5	·	
		6 V	5		5		5		

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	V	T,	4 = 25°C	;	SN54F	IC574	SN74H	IC574	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V	6	11		4		5			
f <sub>max</sub>			4.5 V	30	36		20		24		MHz	
			6 V	36	40		24		28			
			2 V		90	180		270		225		
t <sub>pd</sub>	CLK	Any Q	4.5 V		28	36		54		45	ns	
						6 V		24	31		46	
	ŌĒ	Any Q	2 V		77	150		225		190	ns	
t <sub>en</sub>			4.5 V		26	30		45		38		
			6 V		23	26		38		32		
			2 V		52	150		225		190		
<sup>t</sup> dis	ŌĒ	Any Q	4.5 V		24	30		45		38	ns	
			6 V		22	26		38		32		
			2 V		28	60		90		75		
t <sub>t</sub>		Any Q	4.5 V		8	12		18		15	ns	
			6 V		6	10		15		13		

## SN54HC574, SN74HC574 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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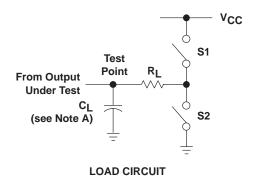
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 150 pF (unless otherwise noted) (see Figure 1)

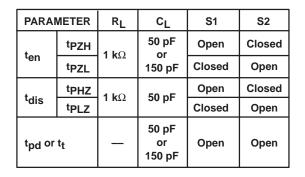
PARAMETER	FROM	то	V	T,	չ = 25°C	;	SN54H	IC574	SN74HC574		UNIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6					5		
f <sub>max</sub>			4.5 V	30					24		MHz
			6 V	36					28		
	CLK	Any Q	2 V		105	265		400		330	
t <sub>pd</sub>			4.5 V		36	53		80		66	66 ns 57
			6 V		31	46		68		57	
			2 V		95	235		355		295	ns
t <sub>en</sub>	ŌĒ	Any Q	4.5 V		32	47		71		59	
			6 V		28	41		60		51	
		Any Q	2 V		60	210		315		265	ns
t <sub>t</sub>			4.5 V		17	42		63		53	
			6 V		14	36		53		45	

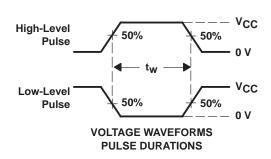
## operating characteristics, $T_A = 25^{\circ}C$

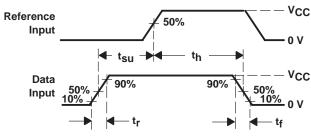
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per flip-flop	No load	100	pF

#### PARAMETER MEASUREMENT INFORMATION

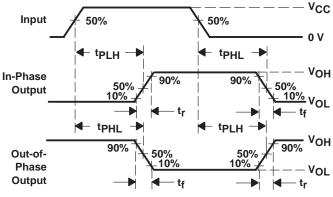


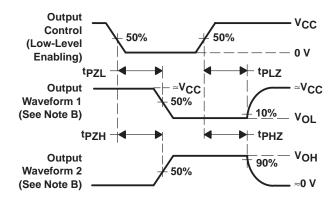






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns, t<sub>f</sub> = 6 ns.
- D. For clock inputs, f<sub>max</sub> is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tpZL and tpZH are the same as ten.
- H. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/65604BRA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN54HC574J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN74HC574DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC574N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74HC574NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574PWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC574PWTE4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54HC574FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC574J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC574W	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check



#### PACKAGE OPTION ADDENDUM

26-Sep-2005

http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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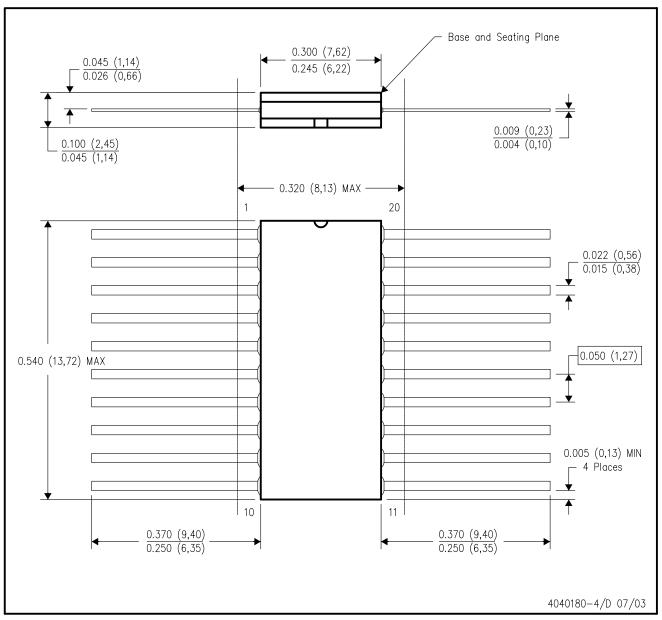
#### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## W (R-GDFP-F20)

## CERAMIC DUAL FLATPACK



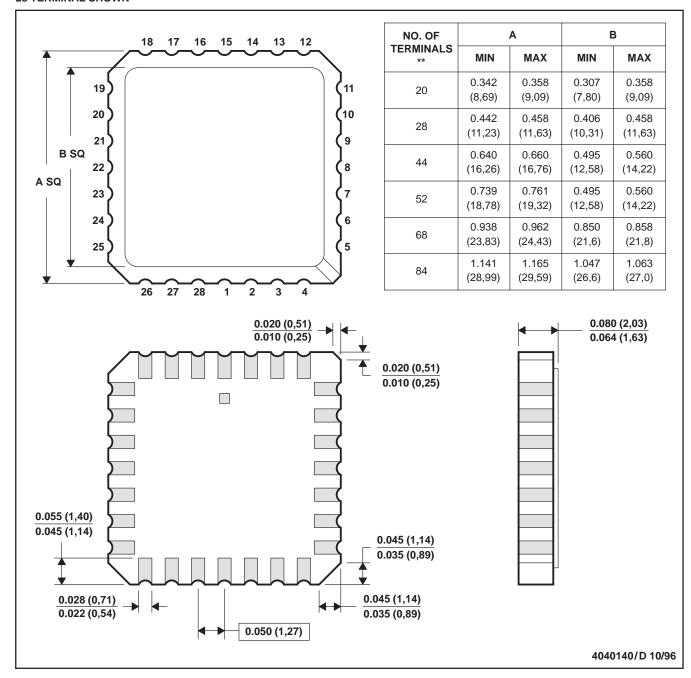
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

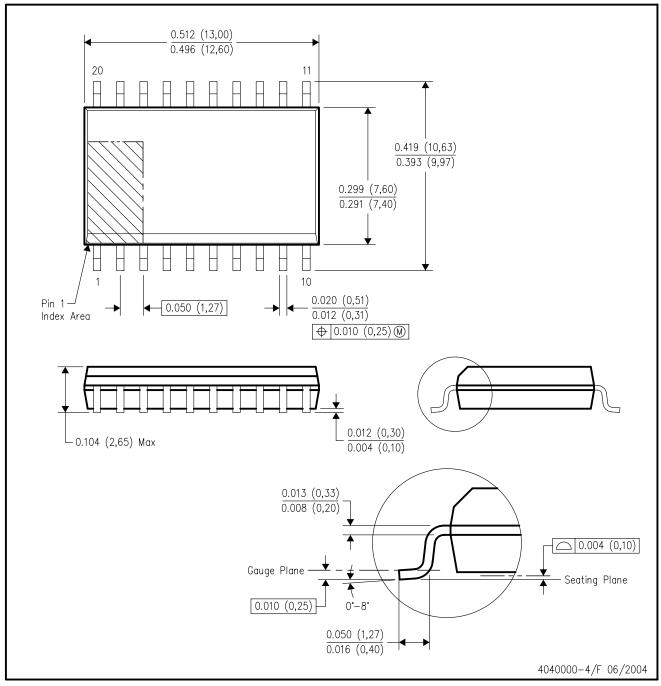


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



## DW (R-PDSO-G20)

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

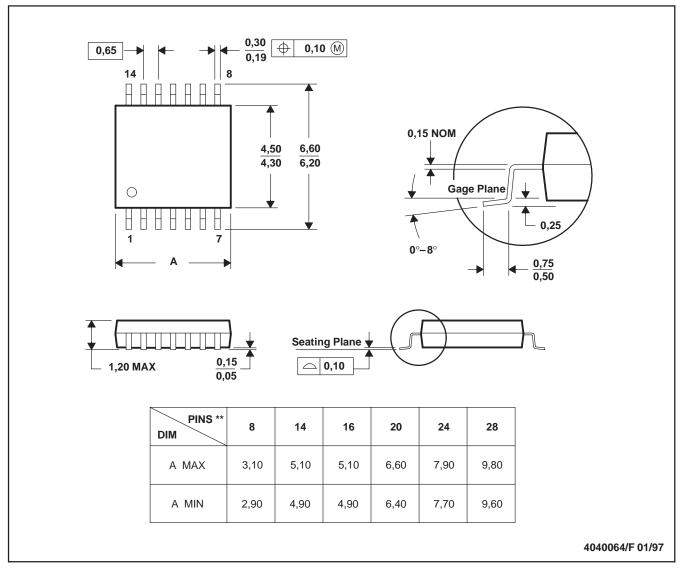
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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